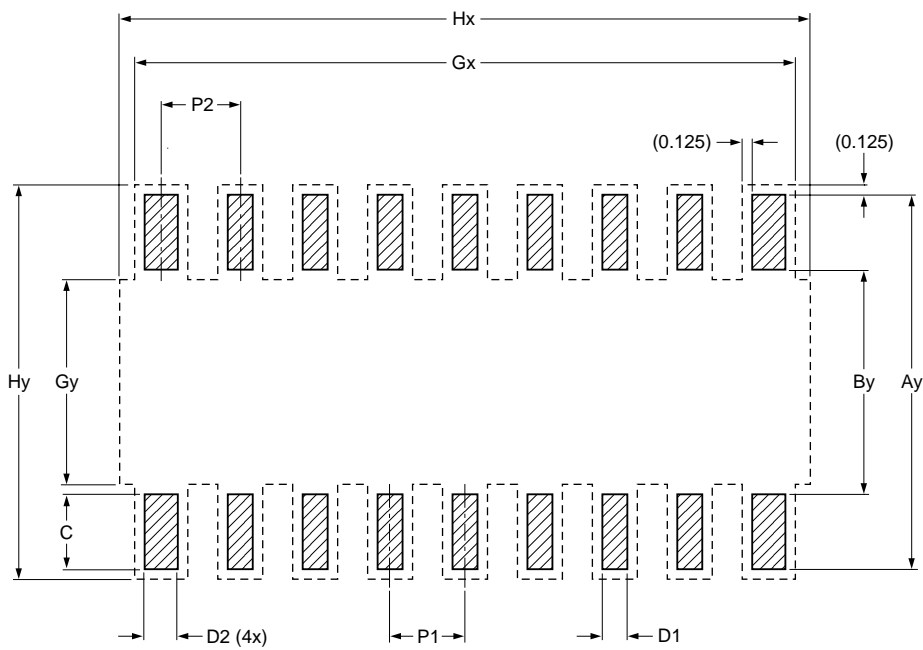




Footprint information for reflow soldering of VSSOP8 package

SOT765-1



Generic footprint pattern
Refer to the package outline drawing for actual layout

 solder land
 occupied area

DIMENSIONS in mm

P1	P2	Ay	By	C	D1	D2	Gx	Gy	Hx	Hy
0.500	0.550	3.500	2.000	0.750	0.300	0.400	2.250	2.800	2.500	3.750